

数字集成电路设计自动化

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2024年10月16日

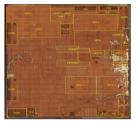
My Curriculum Vitae

- B. Eng Harbin Institute of Technology 2007 2011
- PhD Nanyang Technological University 2011 2016
 School of Electrical and Electronic Engineering
- Post-Doc Nanyang Technological University 2015 2016
- Senior Engineer Huawei Technologies 2016 2020
 Computing Theory & Architecture
- Faculty South China University of Technology since 2021
- Research: 1) Emerging computing architecture
 - 2) Hardware Security
 - 3) Hardware Acceleration for EDA
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Outline

- Digital Design Flow from a IC design perspective
- Simulation
- Synthesis
- Placement
- Routing

Era of Billion-Transistor Chips



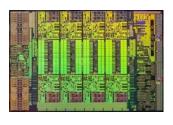
Apple A11 ~4B transistors (?)



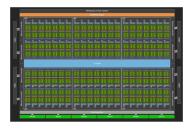
Oracle SPARC M7 ~10B transistors



Xilinx VU9P ~ 35B transistors



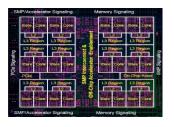
Intel Haswell-EP Xeon E5 ~7B transistors



NVIDIA V100 Pascal ~21B transistors



Apple M1 ~ 57B transistors



IBM Power9 ~8B transistors



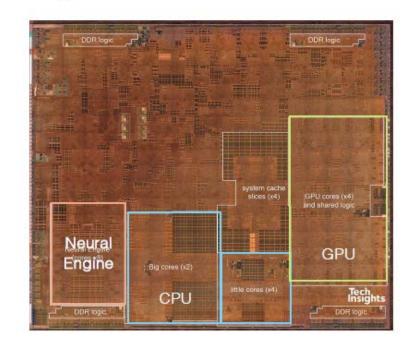
Intel/Altera Stratix 10 ~30B transistors



Cerebras WSE-2 ~ 2.6T transistors

Modern System-On-Chip (SoC)

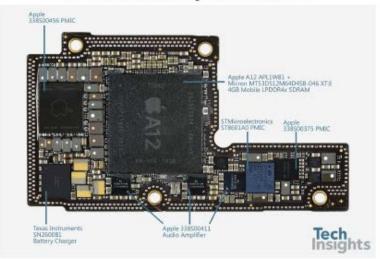
Apple A12



TechInsights

- 7nm CMOS
- Up to 2.49GHz

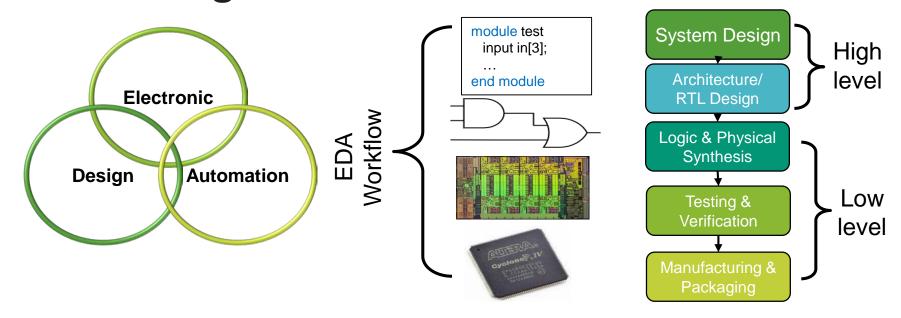
- 2x Large CPUs
- 4x Small CPUs
- GPUs
- Neural processing unit (NPU)
- Lots of memory
- DDR memory interfaces





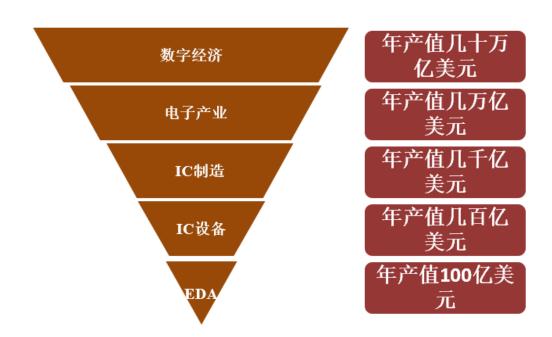
iPhone XS, 2018

Electronic Design Automation



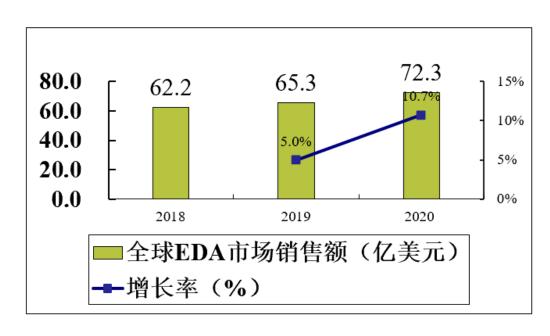
- EDA: a general methodology for refining a high-level description down to a detailed physical implementation for designs
 - integrated circuits (including system-on-chips),
 - and electronic systems
- Modeling, synthesis, and verification at every level of abstraction

全球EDA市场近期持续保持增长



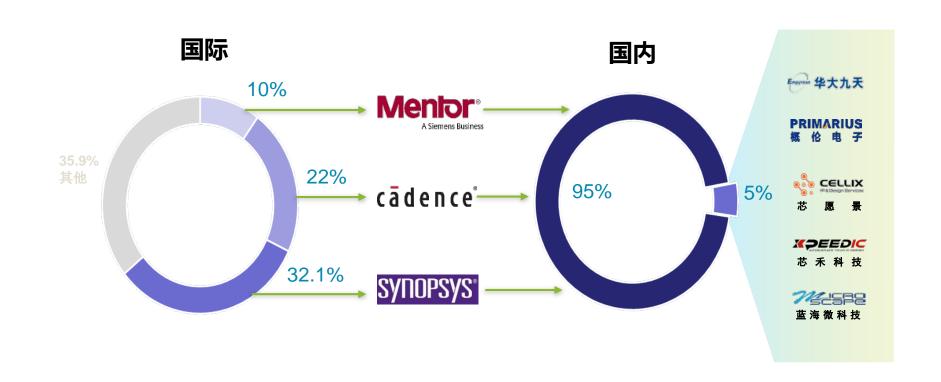
半导体产业链倒金字塔结构

2018-2020年全球EDA市场销售额



2018-2020年全球EDA工具市场竞争格局

芯片之母 --- EDA



Synopsys

- 高层次综合: Synphony
- ► 逻辑综合: Design Compiler
- ► 逻辑仿真: VCS
- ► 形式验证: Formality
- ► 测试生成: TestMax
- ► 时序分析: Primetime
- 物理实现: IC Compiler II
- 物理验证: IC Validator

Cadence

■ 高层次综合: Stratus

►逻辑综合: Genus

►逻辑仿真: Xcelium

→ 形式验证: Conformal Equivalence Checker

■ 时序分析: Tempus

► 物理实现: Innovus

■ 时序建库: Liberate

►物理验证: PVS

Mentor

- 高层次综合: Catapult
- ► 仿真工具: Modelsim
- ► 物理验证: Calibre
- ► 后端工具: Olympus
- DFT: BSDArchit
- MBIST: MBIST Architect
- ATPG: Test Kompress

国产工具: 前端设计验证工具

- ▶ 目前正在开发前端设计验证工具的公司,包括硬件加速器
 - 芯华章
 - 合见工软
 - 思尔芯
- ■主要困难
 - 效率与规模与国外工具尚存差距

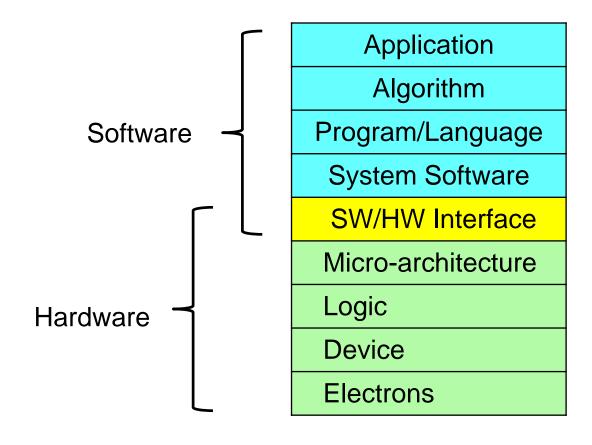
国产工具:后端工具

- 目前正在开发后端工具的公司
 - 鸿芯微纳
 - 立芯
 - 南京E创
 - 上海伴芯
- ■主要困难
 - 模型、规模、效率、流程、先进工艺、时序收敛

国产工具: 签核工具

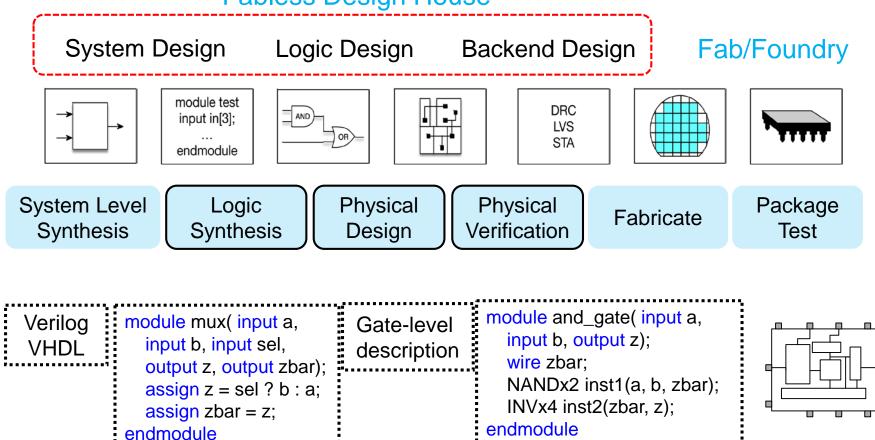
- 目前正在开发签核工具的公司
 - 华大九天(仿真、参数提取、物理验证等)
 - 行芯科技(参数提取、时序分析、可靠性分析等)
- ■主要困难
 - 模型校准
 - 效率、并行与规模

EDA: Cross-layer



IC Design Flow

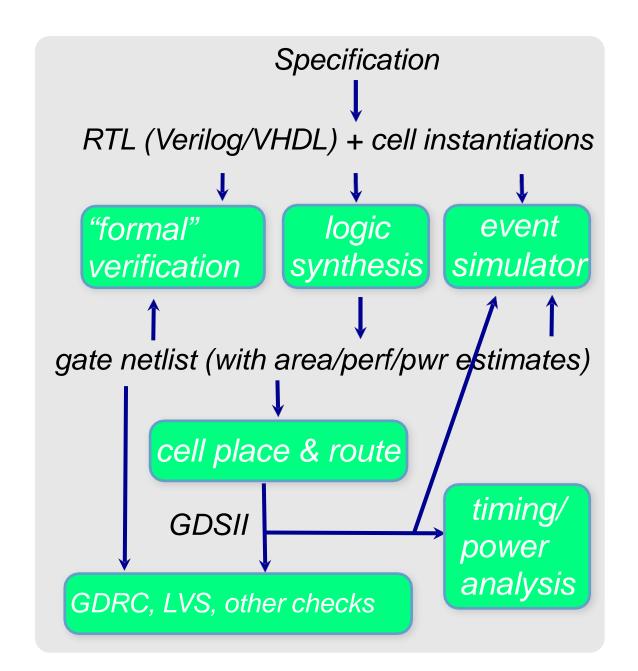
Fabless Design House



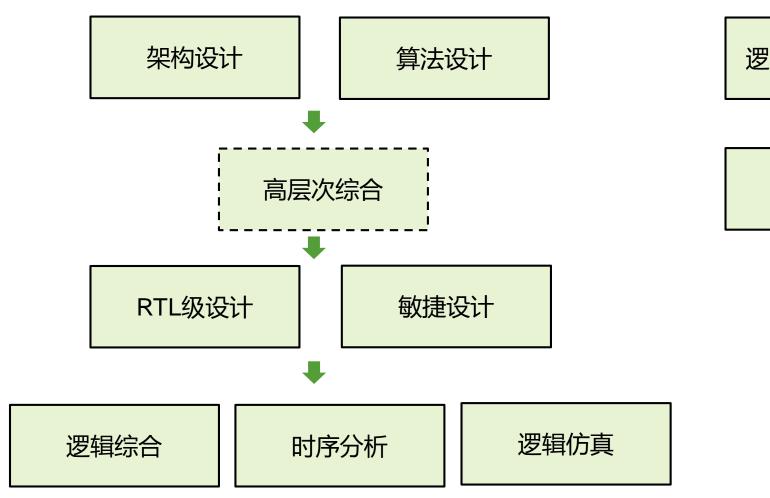
IC Design Flow

RTL Synthesis Based

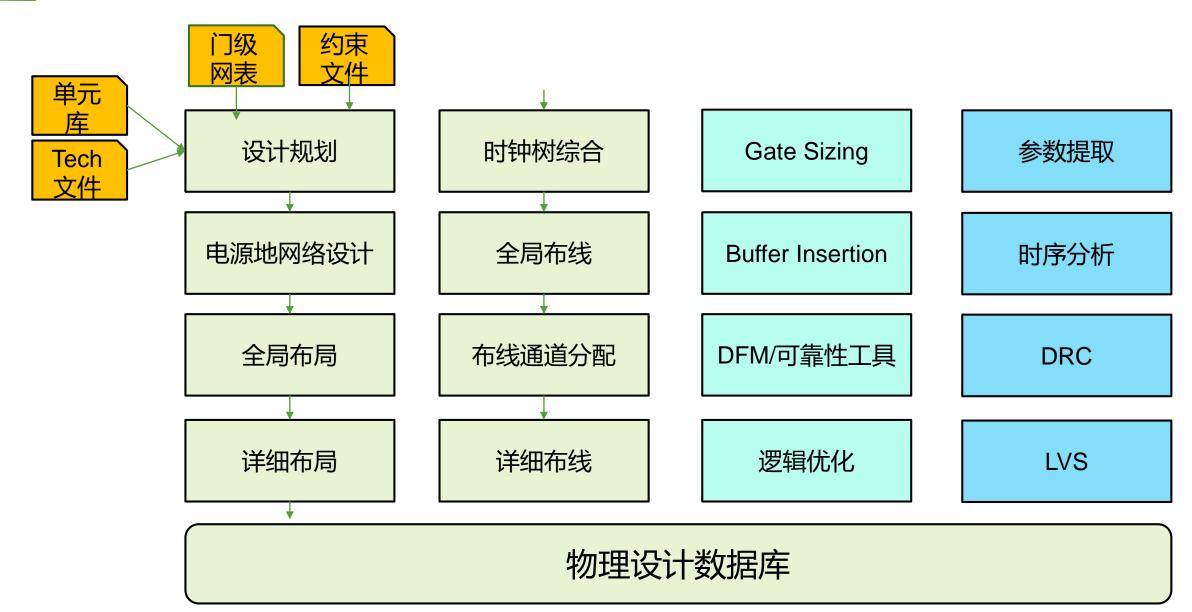
- HDL specifies design as combinational logic + state elements
- Logic Synthesis converts
 hardware description to gate
 and flip-flop implementation
 Cell instantiations needed for
 blocks not inferred by synthesis
 (typically RAM)
- Event simulation verifies RTL
- "Formal" verification compares logical structure of gate netlist to RTL
- Place & route generates layout
- Timing and power checked statically
- Layout verified with LVS and GDRC



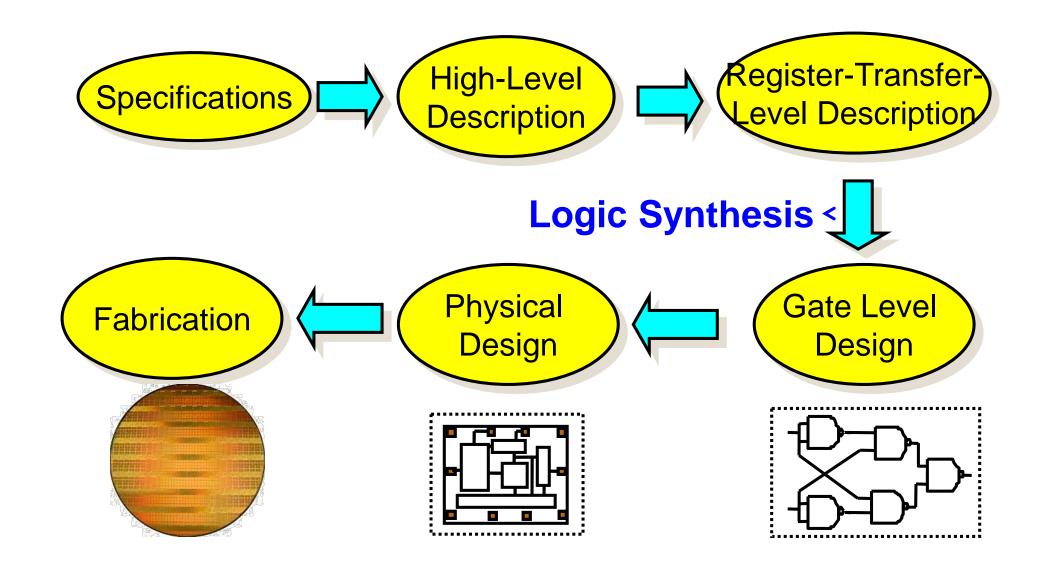
IC Design Flow - frontend



IC Design Flow - backend



IC Design Steps



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RTL

- RTL级描述语言的发展推动了数字集成电路的自动化
- RTL级描述的是寄存器之间的逻辑功能
 - 逻辑和寄存器都可映射为电路单元
 - 可以描述并发和时序

```
CL\overline{K}
In \qquad \qquad R_1 \qquad Combinational \\ Logic \qquad C_{out} \qquad R_2 \qquad Out
```

Logic Simulation

- ■逻辑仿真是逻辑设计验证和调试的重要步骤。逻辑仿真又可以分为 RTL级仿真和门级仿真两类
 - -RTL级仿真用于功能的仿真和调试,缺乏精确的时序信息
 - 一门级仿真可以将门延迟和互连线延迟同时考虑进去,获得更加精确的仿真结果

Logic Simulation

- Event-driven
 - 根据事件, 更新仿真结果, 生成新的事件
- Cycle-based
 - 不考虑cycle内部延迟
 - 速度更快

Emulation

■ 逻辑仿真包括RTL级仿真和门级仿真,都是事件驱动或存在拓扑上的相互关系,导致仿真并行程度难以大规模提升。对于大规模电路,特别是现代集成电路中的SoC系统,逻辑仿真的效率无法满足全系统仿真验证的需求

■ 基于硬件仿真器如FPGA和布尔处理器的方法直接利用硬件门或布尔处理器来仿真逻辑门,利用直接互连或存储数据交换来模拟门之间的连接关系,可以有效

的提升仿真的效率

Cadence Palladium Z1



Synopsys Zebu

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Logic Synthesis

RTL design description





Connected gates + wires in your technology.

Called "netlist"

module and_gate(input a, module mux(input a, Verilog Gate-level input b, output z); input b, input sel, **VHDL** description wire zbar; output z, output zbar); NANDx2 inst1(a, b, zbar); assign z = sel ? b : a;INVx4 inst2(zbar, z); assign zbar = z; endmodule endmodule

约束文件 (tcl)

Tool command Language

```
# TOP MODULE NAME

#-----
set top_module inno_ddrn_ctrl_ip

# SYSTEM CLOCK PERIOD

#-----
set clk_period 3.3 # make even smaller
set nn_clk_period 3.3 #
set ok_clk_period 10 #
set spi_clk_period 10 #
```

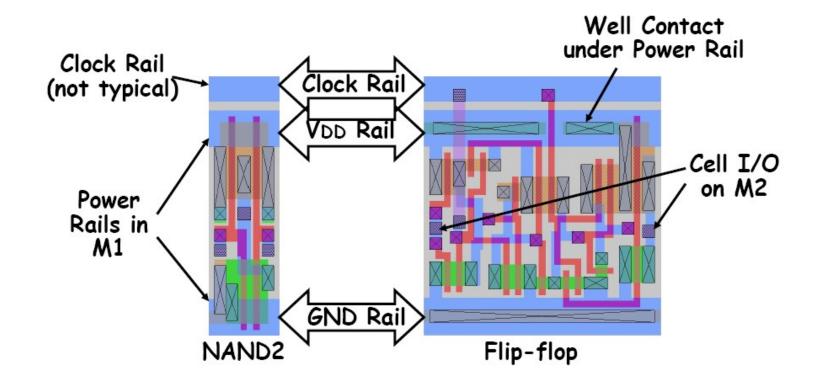
```
set input delay
                    [expr $ok clk period * 0.6] -clock v okClk [get ports pad epPipeWrite]
set input delay
                    [expr $ok clk period * 0.6] -clock v okClk [get ports
                                                                           pad epPipeIn[*]]
                  [expr $ok clk period * 0.6] -clock v okClk [get ports
set input delay
                                                                           pad epPipeRead]
                   [expr $ok clk period * 0.6] -clock v okClk [get ports
set output delay
                                                                           pad epPipeOut[*]]
set output delay
                   [expr $ok clk period * 0.6] -clock v okClk [get ports
                                                                           pad ep60trig 0]
set output delay
                    [expr $ok clk period * 0.6] -clock v okClk [get ports
                                                                           pad ep60trig 2]
                   [expr $ok clk period * 0.6] -clock v okClk [get ports
set output delay
                                                                           pad ep60trig 3]
                    [expr $ok clk period * 0.6] -clock v okClk [get ports pad ep60trig 4]
set output delay
set output delay
                    [expr $ok clk period * 0.6] -clock v okClk [get ports pad ep60trig 5]
                    [expr $spi clk period * 0.6] -clock v spi clk [get ports pad i SPI CS n]
set input delay
                    [expr $spi clk period * 0.6] -clock v spi clk [get ports pad i SPI MOSI]
set input delay
set output delay
                    [expr $spi clk period * 0.6] -clock v spi clk [get ports pad o SPI MISO]
set output delay
                    [expr $nn clk period * 0.6] -clock v nn clk [get ports pad error]
```

```
#create_clock -name nn_clk -period $nn_clk_period [get_ports pad_nn_clk]
create_clock -name nn_clk -period $nn_clk_period [get_ports clk]
create_clock -name v_nn_clk -period $nn_clk_period

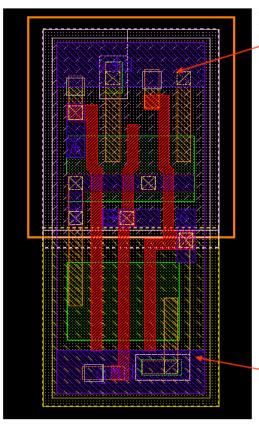
set_clock_uncertainty -setup 0.2 nn_clk
set_clock_uncertainty -hold 0.1 nn_clk
```

Standard Cell

Cells have standard height but vary in width Designed to connect power, ground, and wells by abutment



Standard Cell



Power Supply Line (V_{DD}) Delay in (ns)!!

Path	1.2V - 125°C	1.6V - 40°C
$In 1-t_{pLH}$	0.073+7.98C+0.317T	0.020+2.73 <i>C</i> +0.253 <i>T</i>
$In 1-t_{pHL}$	0.069+8.43 <i>C</i> +0.364 <i>T</i>	0.018+2.14 <i>C</i> +0.292 <i>T</i>
In2—t _{pLH}	0.101+7.97C+0.318T	0.026+2.38 <i>C</i> +0.255 <i>T</i>
$In2-t_{pHL}$	0.097+8.42 <i>C</i> +0.325 <i>T</i>	0.023+2.14 <i>C</i> +0.269 <i>T</i>
$In3-t_{pLH}$	0.120+8.00 <i>C</i> +0.318 <i>T</i>	0.031+2.37 <i>C</i> +0.258 <i>T</i>
$In3-t_{pHL}$	0.110+8.41 <i>C</i> +0.280 <i>T</i>	0.027+2.15 <i>C</i> +0.223 <i>T</i>

3-input NAND cell

(from ST Microelectronics):

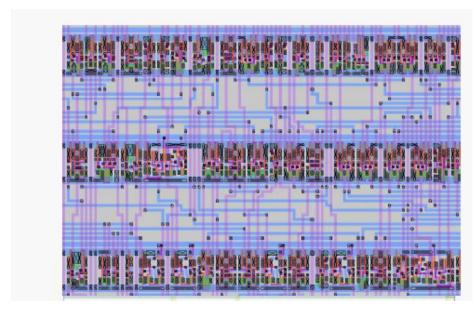
C = Load capacitance

T = input rise/fall time

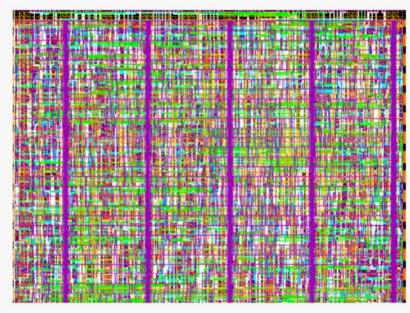
Ground Supply Line (GND)

 Each library cell (FF, NAND, NOR, INV, etc.) and the variations on size (strength of the gate) is fully characterized across temperature, loading, etc.

Standard Cell



1um, 2-metal process

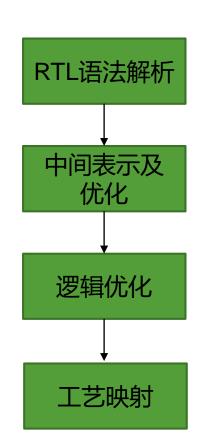


Modern sub-100nm process "Transistors are free things that fit under wires"

- With limited # metal layers, dedicated routing channels were needed
- Currently area dominated by wires

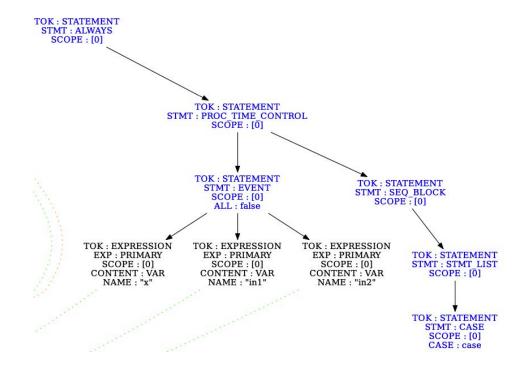
逻辑综合基本过程

- 逻辑综合与高级语言编译类似,基于多层的中间表示和不同的 pass对中间表示进行优化
- ▶ 中间表示优化与前端语言无关,与工艺无关
- 后端工艺映射再将工艺无关优化结果映射为实际工艺实现
- 一般可以包含两种级别的中间表示
 - RTL级中间表示: 用于RTL级的优化及逻辑综合
 - 逻辑级中间表示: 用于逻辑优化



逻辑综合 - 前端

■ RTL语法解析将RTL语言转化为抽象语法树(AST),并提供访问函数接口来遍历抽象语法树上的节点



RTL语言工艺无关的中间表示

- 在生成抽象语法树后,逻辑综合的前端一般也会维持一个类似LLVM的中间表示结构
- 逻辑综合的RTL级中间表示,
 - 基本的module/procedure等RTL级表示,
 - 基本的抽象逻辑、计算单元和原语如寄存器、与或非单元、加减乘除基本运算单元、MUX单元、存储器等

抽象语法树到RTL中间表示的转换

- 根据RTL语法进行推断转换,将一些控制、计算转换成对应抽象逻辑、 计算单元和原语,这些转换包括但不限于:
 - 将if/else和switch/case等语法转化为MUX原语;
 - 将基本的与或非转化为基本抽象逻辑单元;
 - 将加减乘除等操作转化为基本的抽象计算单元;
 - 根据RTL语义,推断出寄存器单元和存储单元

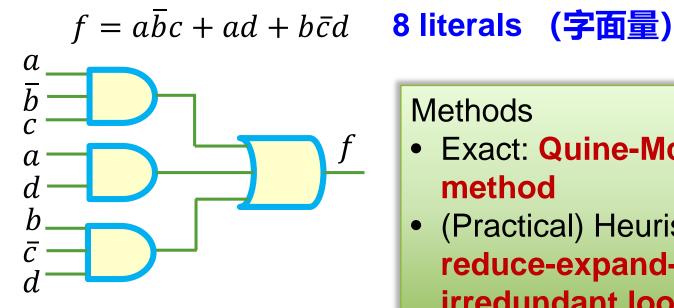
```
cell $adff $procdff$6
        parameter \ARST_POLARITY 1'1
        parameter \ARST_VALUE 1'0
        parameter \CLK_POLARITY 1'1
        parameter \WIDTH 1
        connect \ARST \reset
        connect \CLK \clock
        connect \D $0\q[0:0]
        connect \Q \q
end
cell $mux $procmux$3
        parameter \WIDTH 1
        connect \A \q
        connect \B \d
        connect \S \enable
        connect Y $0 q[0:0]
end
```

逻辑优化

- 逻辑优化是逻辑综合的关键步骤
- 早期的逻辑优化:工艺相关的逻辑优化。基于规则,针对门级网表,构建一个优化窗口,对窗口内的门电路依据实际实现进行优化。规则多,且随着单元电路加入会快速增加
- 逻辑优化的发展: 工艺无关的逻辑优化+工艺映射。中间表示与工艺无关, 但可以表征最终实现后的代价。工艺映射再将中间表示面向特定工艺进行映射
- ▶ 商用工具: 工艺无关优化+逻辑映射+基于规则的映射后优化
- 两层逻辑优化 多级逻辑电路

Two-Level Logic Design

- A logic implementation based on sum-of-products (SOP) expression.
 - First level: many AND gates.
 - Second level: one "big" OR gate.
- Optimization target: minimize **number of literals**

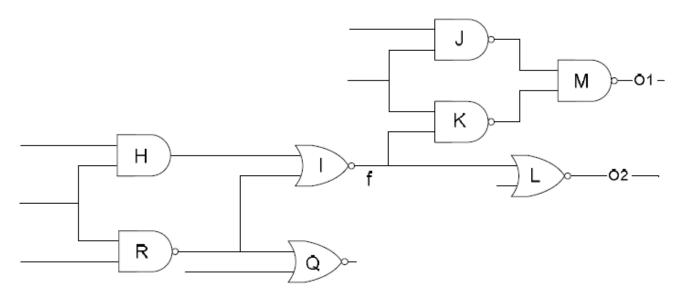


Methods

- Exact: Quine-McCluskey method
- (Practical) Heuristic: reduce-expandirredundant loop

Multi-Level Design

Modern design style!



- Two phases in multi-level logic synthesis:
 - Technology-independent synthesis
 - Technology mapping

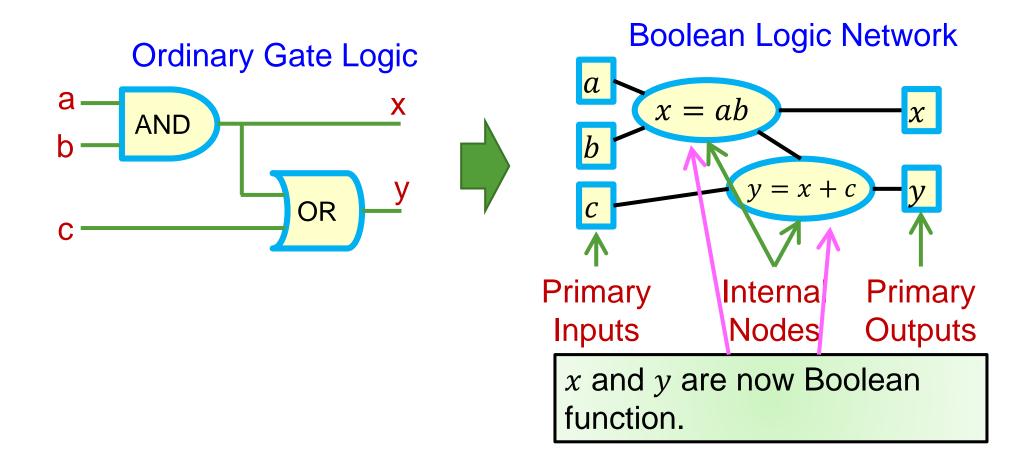
Technology-Independent Synthesis

- Output: An abstract representation of Boolean function
 - It is not the actual gate-level netlist
 - The result is called: "technology independent" logic or "uncommitted" logic
 - Example: AND-inverter graph (AIG), Boolean logic network, etc.

AND-inverter graph (AIG) •: inverter

Boolean Logic Network Model

■ A graph of connected blocks, like any logic diagram, but now individual component blocks are 2-level Boolean functions in SOP form.

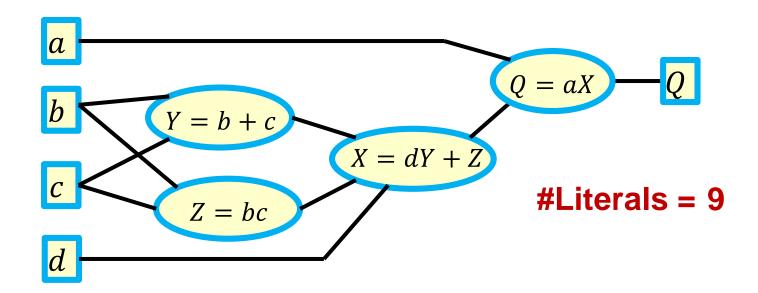


Boolean Logic Network: What to Optimize?

A simplistic but surprisingly useful metric:

Total literal count

- Count every appearance of every variable on <u>right hand side</u> of "=" in every internal node.
- Delays also matter, but here only focus on area.



Optimizing Multilevel Logic: Big Ideas

- **Boolean logic network** is a **data structure**. So, what **operators** do we need?
- 3 basic kinds of operators:
 - Simplify network nodes: no change in # of nodes, just simplify insides, which are SOP form.
 - Remove network nodes: take "too small" nodes, substitute them back into fanouts.
 - This is not too hard. This is mostly manipulating the graph, simple SOP edits.
 - Add new network nodes: this is factoring. Take big nodes, split into smaller nodes.
 - This is a **big deal** and takes effort.

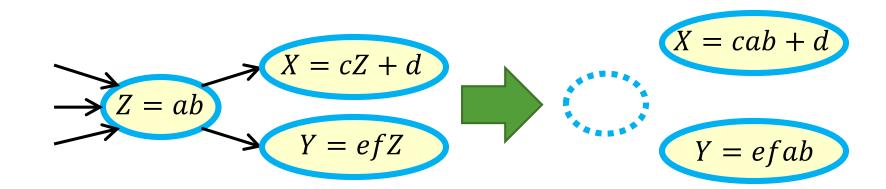
Simplifying a Node

- This is **2-level synthesis**.
- Just run ESPRESSO on 2-level form inside the node, to reduce # literals.
- As structural changes happen across network, "insides" of nodes may present opportunity to simplify.



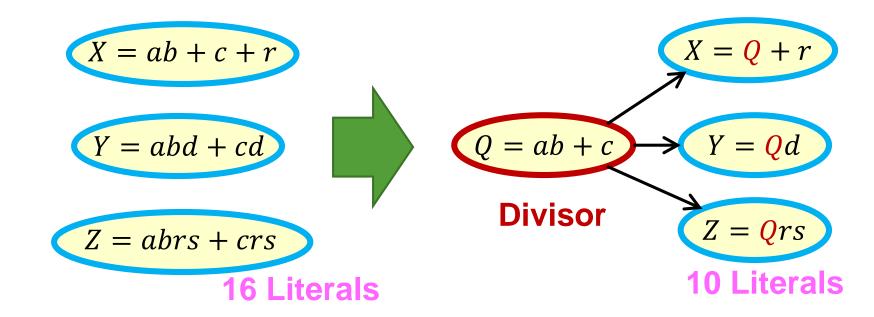
Removing a Node

- Typical case is you have a "small" factor which doesn't seem to be worth making it a separate node.
- "Push" it back into its fanouts, make those nodes bigger, and hope you can use 2-level simplification on them.



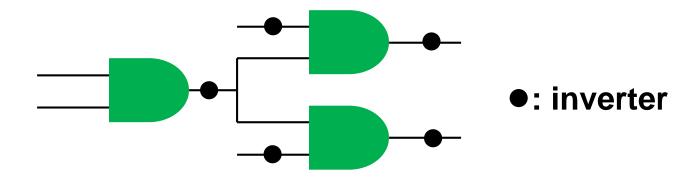
Adding new Nodes

- Look at existing nodes, identify **common divisors**, extract them, connect as **fanins**.
- Tradeoff: more delay (another level of logic), but fewer literals (less gate area).
- Based on algebraic model, algebraic division, kernels



AND-Inverter Graphs (AIGs)

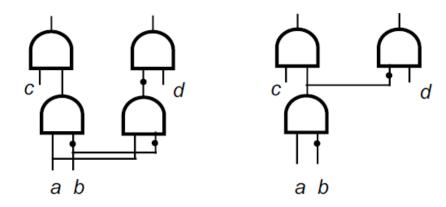
Any Boolean function can be represented as an AIG!



- But AIG is not canonical
 - For the same function, many different AIG representations.
- For area reduction, minimize the number of AND nodes.
- Tool: ABC: A System for Sequential Synthesis and Verification
 - http://www.eecs.berkeley.edu/~alanmi/abc

AIG Structural Hashing (Strashing)

- When building AIGs, always add AND node
 - When an AIG is constructed without strashing, AND gates are added one at a time without checking whether AND gate with the same fanins already exists
- One-level strashing
 - When adding a new AND-node, check the hash table for a node with the same input pair (fanin)
 - If it exists, return it; otherwise, create a new node



AIG Optimization Operations

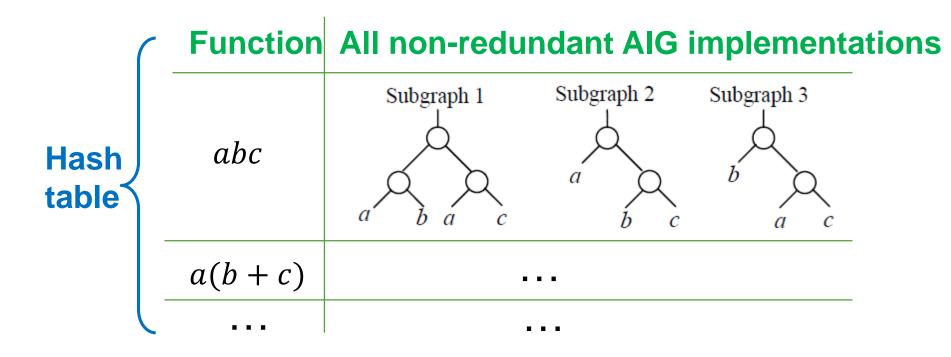
- Rewriting
- Resubstitution
- Balancing
- Refactoring





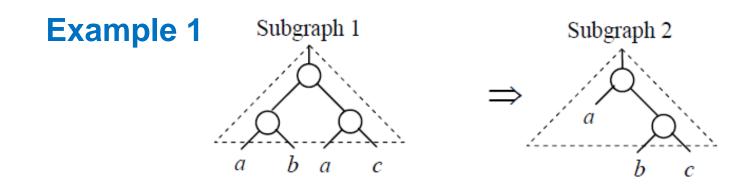
Rewriting: Phase 1

- All two-level AIG subgraphs are pre-computed and stored in a hash table by their functionality.
- The table contains all non-redundant AIG implementations of logic functions with four variables or less



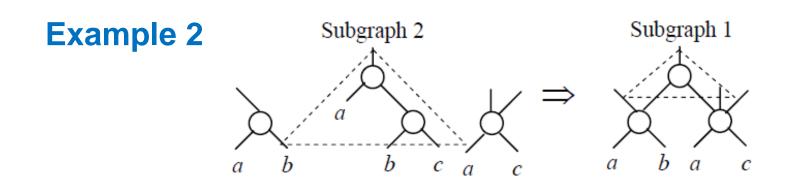
Rewriting: Phase 2

- ► For each node in topological order, find its two-level AIG subgraph and compute its Boolean function.
- Use the function to access the hash table to find equivalent subgraphs.
- Try each subgraph, while taking into account logic sharing between the new subgraph nodes and the existing nodes.
- Choose the subgraph with largest save in # of nodes.



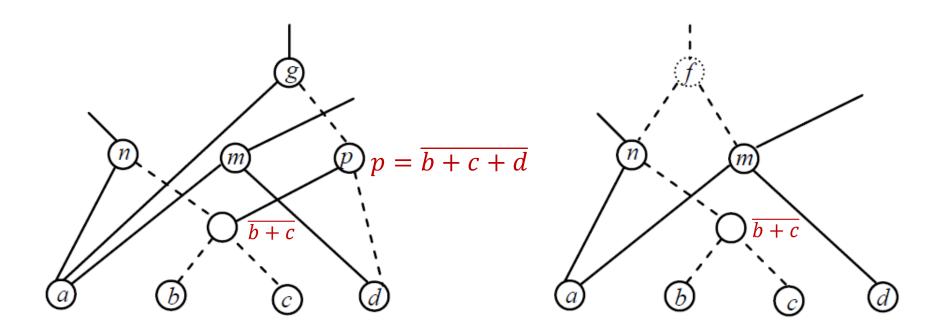
Rewriting: Phase 2

- ► For each node in topological order, find its two-level AIG subgraph and compute its Boolean function.
- Use the function to access the hash table to find equivalent subgraphs.
- Try each subgraph, while taking into account logic sharing between the new subgraph nodes and the existing nodes.
- Choose the subgraph with largest save in # of nodes.



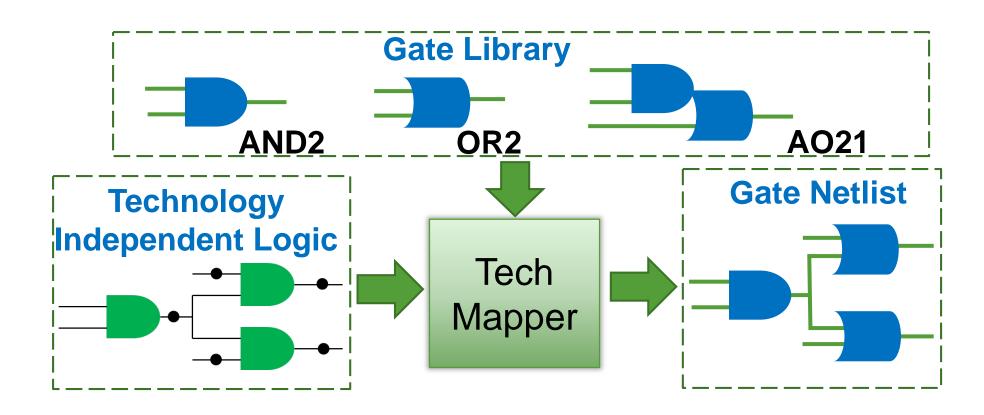
Resubstitution

- Express the function of a node using other nodes (divisors).
- Example:
 - Replace function g = a(b+c+d) as f = n+m, where n = a(b+c) and m = ad



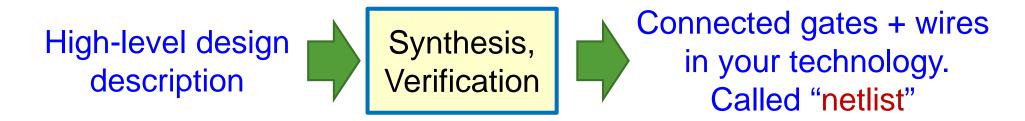
Technology Mapping

 \blacksquare Given a gate library, from which we can pick gates, and **technology independent** logic F, build a final **gate netlist** for F using only these gates from the given library.



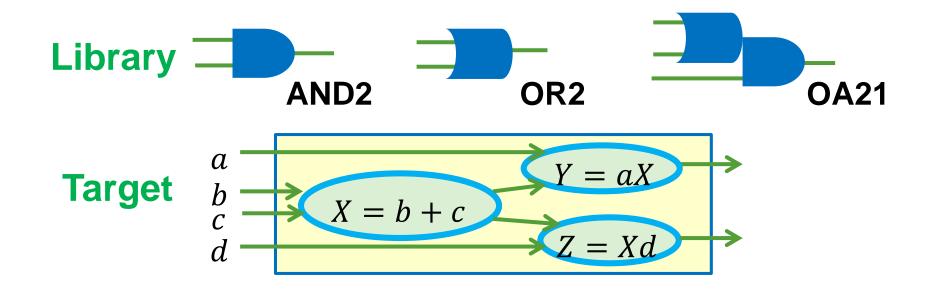
From Logic... To Layout...

- What you know...
 - Computational Boolean algebra, representation, some verification, some synthesis.
 - This is what happens in the "front end" of the ASIC design process.

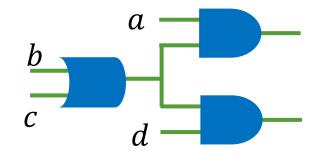


- One key connecting step:
 - How to transform result of multi-level synthesis into real gates for layout task.
 - Called: Technology Mapping, or Tech Mapping.

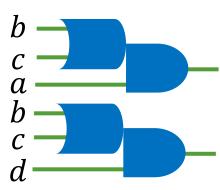
Tech Mapping: Simple Example



Obvious Mapping

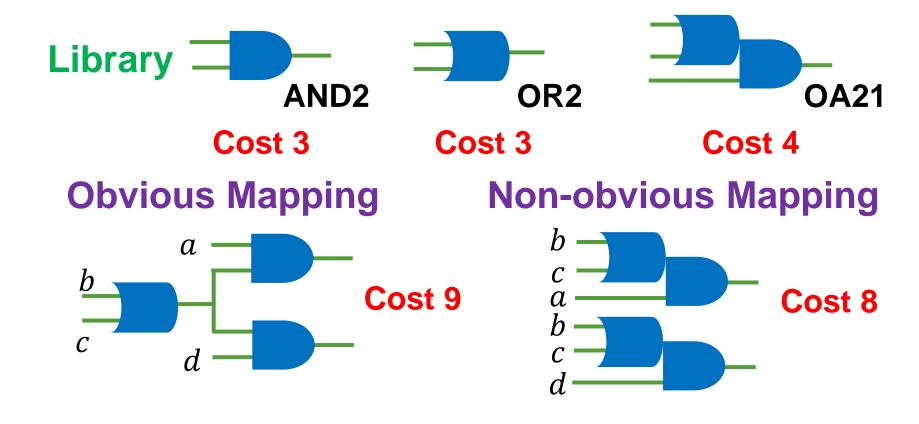


Non-obvious Mapping



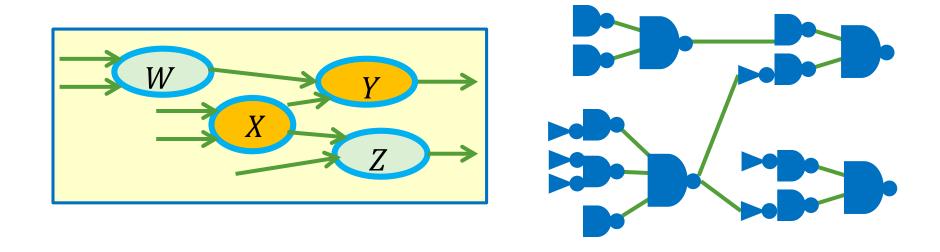
Tech Mapping

- Why choose a non-obvious mapping?
 - Answer 1: Cost. Suppose each gate in library has a cost associated with it, e.g., the silicon area of the standard cell gate.



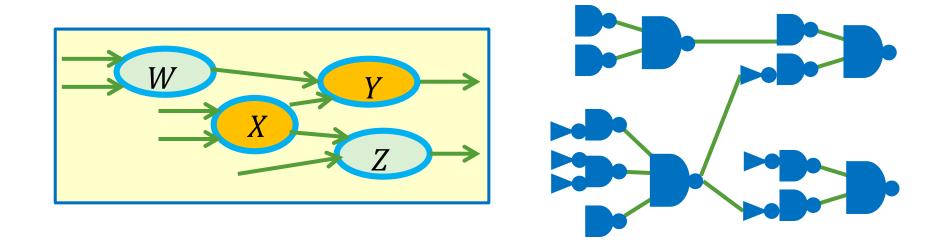
What "Technology Mapping" Does?

- By transforming every SOP form in each node into NAND & NOT gates ...
 - $-\dots$ Boolean logic network **disappears**. W, X, Y, Z boundaries go away.
 - We have one BIG "flat" network of NANDs and NOTs. This is what we are going to map.



Technology Mapping

- Multi-level synthesis produces this big network of simple gates.
- How to transform map this onto standard cells in our library?

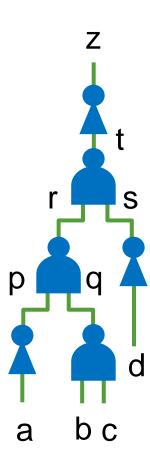


Technology Mapping as Tree Covering

- One famous, simple model of problem:
 - Your logic network to be mapped is a tree of simple gates.
 - We assume uncommitted form is **2-input NAND** ("NAND2") and NOT gates, only.
 - Your library of available "real" gate types is also represented in this form.
 - Each gate is represented as a tree of NAND2 and NOT gates, with associated cost.
- Method is surprisingly simple and optimal.
 - Reference: Kurt Keutzer, "DAGON: Technology Binding and Local Optimization by DAG Matching," Proc. ACM/IEEE
 Design Automation Conference (DAC), 1987.

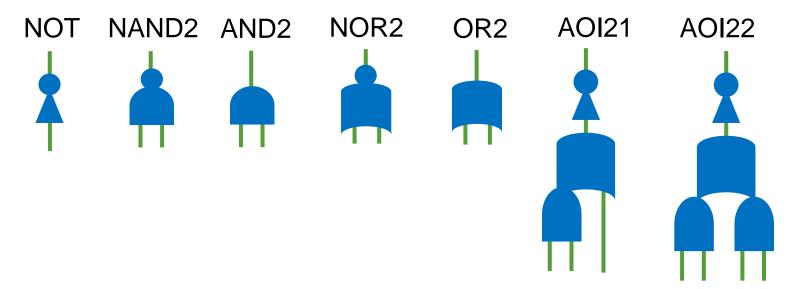
Tree Covering Example: Start with...

- Here is your uncommitted logic to be tech mapped.
 - This is what results from our multi-level synthesis optimization...
 - ... after replacing all SOP forms in the network nodes with NAND2/NOT.
 - Called the subject tree.
 - (Restrict to NAND2 to keep this simple. Also label not only inputs but all internal wires too.)



Tree Covering: Your Technology Library

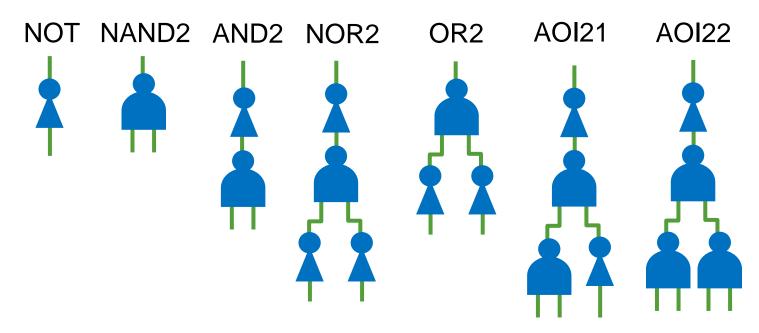
And, here is a very simple technology library.



First problem: this is **not** in the required **NAND2/NOT-only** form. **Must transform**.

Tree Covering: Representing Library

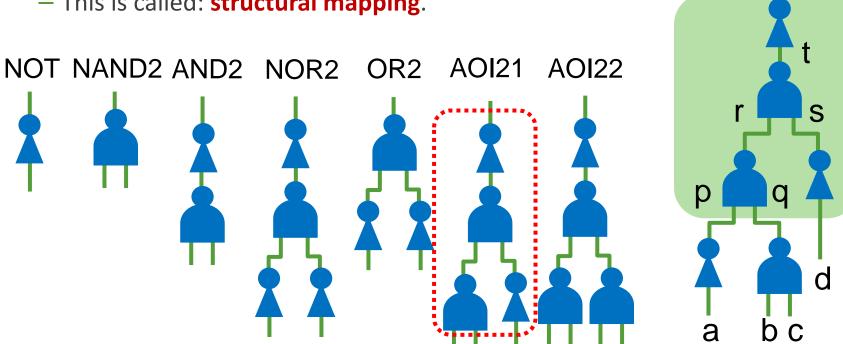
- Transforming to NAND2/NOT form is easy.
 - Just apply De Morgan's law.



Each library element in this form is called a pattern tree.

Essential Idea in "Tree Covering"

- Avoid any Boolean algebra!
- Just do "pattern matching".
 - Find where, in subject graph, the library pattern "matches".
 - NAND matches NAND, NOT matches NOT, etc.
 - This is called: structural mapping.

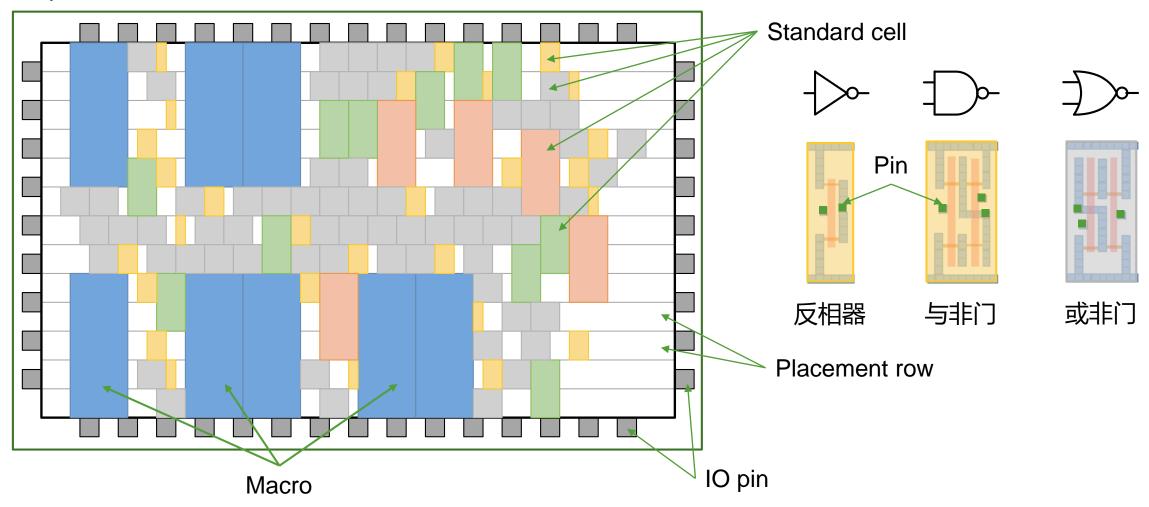


Outline

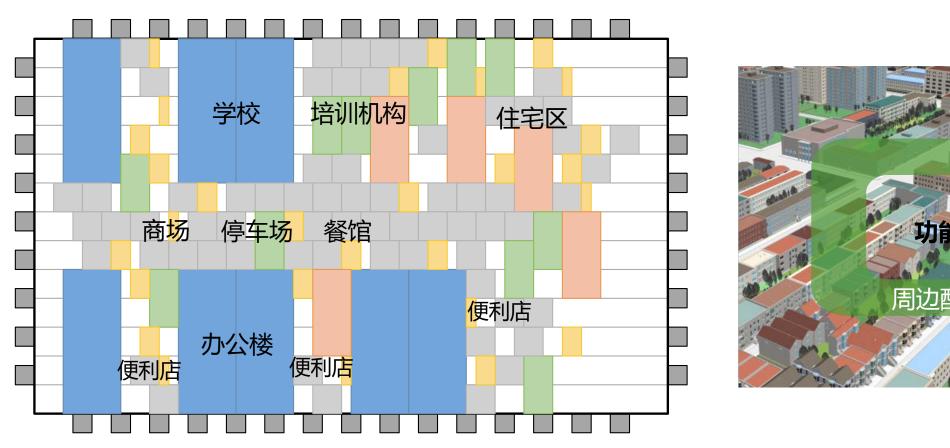
- Digital Design Flow from a IC design perspective
- Simulation
- Synthesis
- Placement
- Routing

What is Placement

Layout



Analog to Urban Planning

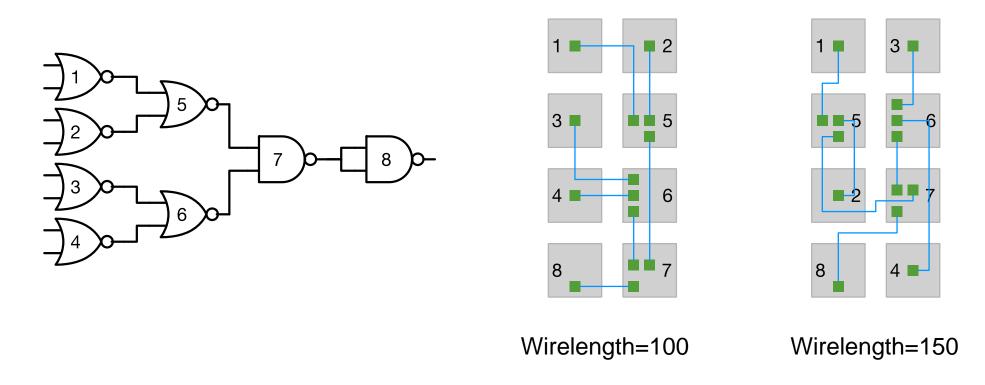




好的城市规划应使功能关联建筑之间的距离尽可能小

Metrics for Placement

Wirelength: length of physical wires connecting cells



好的布局应使相连Cell之间的距离尽可能小

Problem Formulation for Placement

Input

- Blocks (standard cells and macros) B₁, ..., B_n
- Shapes and Pin Positions for each block B_i
- Nets $N_1, ..., N_m$

Output

- Coordinates (x_i, y_i) for block B_i.
- No overlaps between blocks within a fixed layout area

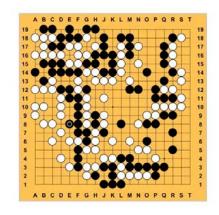
Objective

- The total wirelength is minimized
- Other objectives: timing, routability, clock, buffering

How Difficult Placement is



#states: ~10¹²³



#states: ~10³⁶⁰

Google AlphaGo Train 40 days using 176 GPUs

How Difficult Placement is

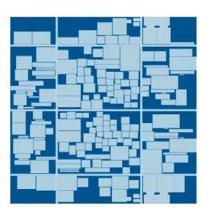
- Huge problem sizes: tens of millions of cells
- Huge solution space: larger than $1K \times 1K$ grids in a layout



#states: ~10¹²³



#states: ~10³⁶⁰



#states: >10^{100,000}

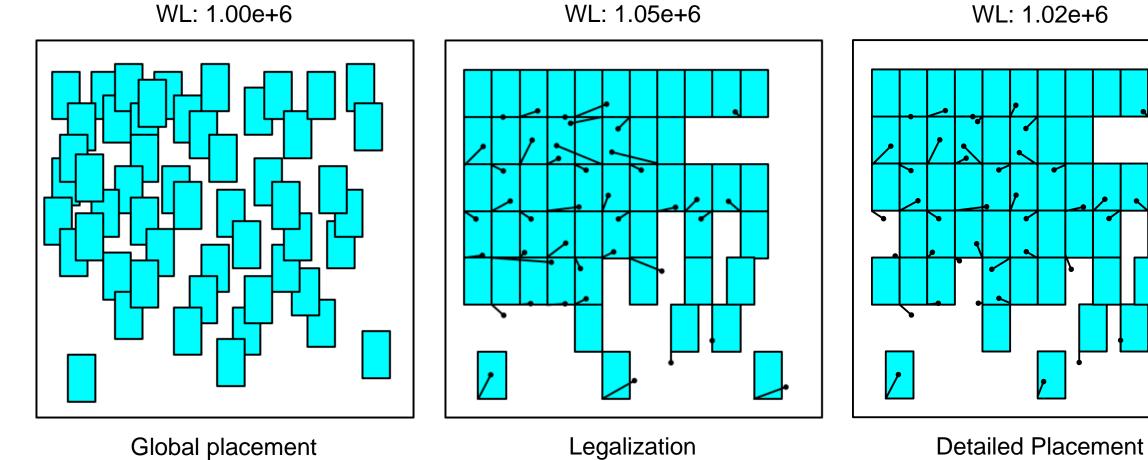
Google AlphaGo Train 40 days using 176 GPUs

Good Placement vs Bad Placement

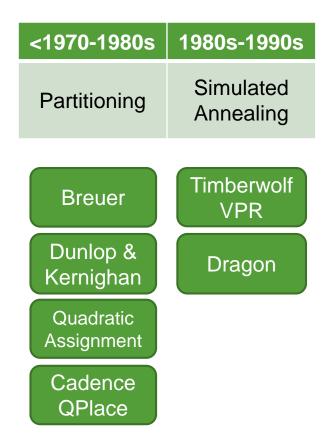
230 cells in FPGA (design e64 in the MCNC benchmark suite)

Random Initial Final Solution Routing Solution WL = 5.47e + 4WL = 6.73e + 3

Typical Placement Flow



The History of Placement Algorithms



The History of Placement Algorithms

<1970-1980s	1980s-1990s	1990s-2010s		>2010s		
Dartitioning	Simulated	Min-Cut	Analytic		Analytic	
Partitioning	Annealing	(Multi-level)	Quadratic	Nonlinear	Quadratic	Nonlinear
Breuer	Timberwolf VPR	FengShui	GORDIAN	APlace	POLAR	ePlace RePlAce
Dunlop & Kernighan	Dragon	Саро	BonnPlace	Naylor Synopsis	SimPL ComPLx	DREAMPlace
Quadratic Assignment		Capo +Rooster	mFar	NTUplace	MAPLE	
Cadence QPlace			Kraftwerk	mPL6		
			FastPlace			
			Warp3			

Simulated Annealing

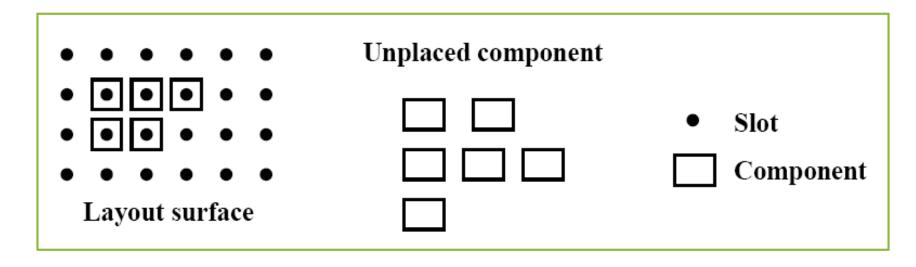
- Timberwolf package [JSSC-85, DAC-86]
 - Sechen, Carl, and Alberto Sangiovanni-Vincentelli. "The TimberWolf placement and routing package." *IEEE Journal of Solid-State Circuits* 20.2 (1985): 510-522.
 - Sechen, Carl, and Alberto Sangiovanni-Vincentelli. "TimberWolf3. 2: A new standard cell placement and global routing package." 23rd ACM/IEEE Design Automation Conference. IEEE, 1986.

Dragon [ICCAD-00]

Yang, Xiaojian, and Majid Sarrafzadeh. "Dragon2000: Standard-cell placement tool for large industry circuits." IEEE/ACM International Conference on Computer Aided Design. ICCAD-2000. IEEE/ACM Digest of Technical Papers (Cat. No. 00CH37140). IEEE, 2000.

A Down-to-the-Earth Method

- Select unplaced components and place them in slots
- SELECT: choose the unplaced component that is most strongly connected to all (or any single) of the placed component
- PLACE: place the selected component at a slot such that a certain "cost" of the partial placement is minimized
- Simple and fast: ideal for initial placement



TimberWolf

Stage 1

- Modules are moved between different rows as well as within the same row
- Module overlaps are allowed
- When the temperature is reduced below a certain value, stage 2 begins

Stage 2

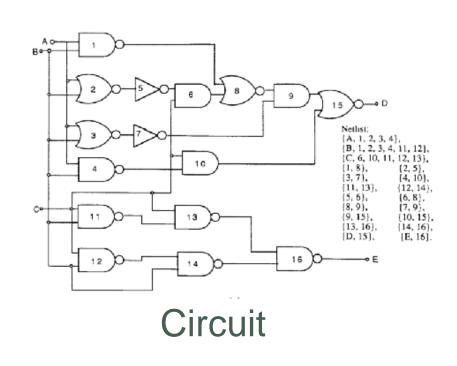
- Remove overlaps
- Annealing process continues, but only interchanges adjacent modules within the same row

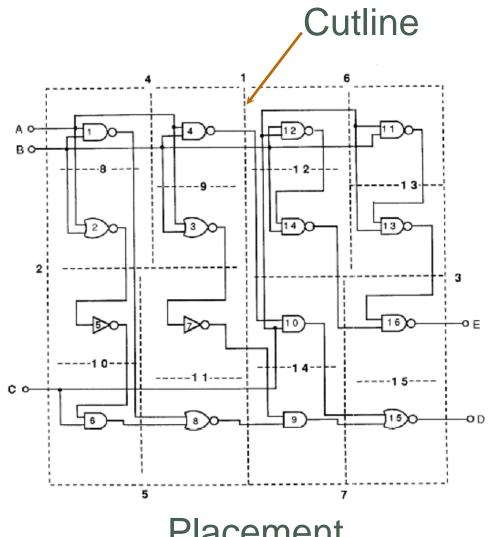
Partitioning-based Approach

- Try to group closely connected modules together.
- Repetitively divide a circuit into sub-circuits such that the cut value is minimized.
- Also, the placement region is partitioned (by <u>cutlines</u>) accordingly.
- Each sub-circuit is assigned to one partition of the placement region.

Note: Also called min-cut placement approach.

An Example



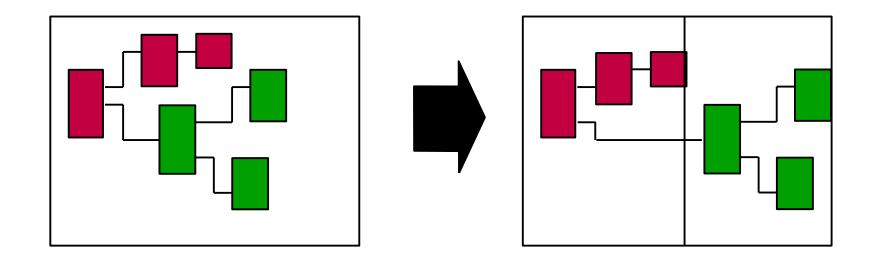


Placement

Partitioning

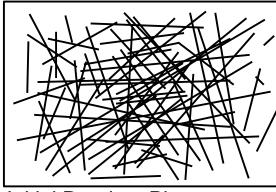
Objective:

 Given a set of interconnected blocks, produce two sets that are of equal size, and such that the number of nets connecting the two sets is minimized.

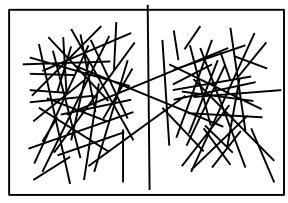


FM Partitioning

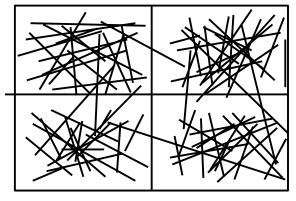
```
list_of_sets = entire_chip;
while(any_set_has_2_or_more_objects(list_of_sets))
{
    for_each_set_in(list_of_sets)
    {
        partition_it();
    }
    /* each time through this loop the number of */
    /* sets in the list doubles. */
}
```



Initial Random Placement



After Cut 1

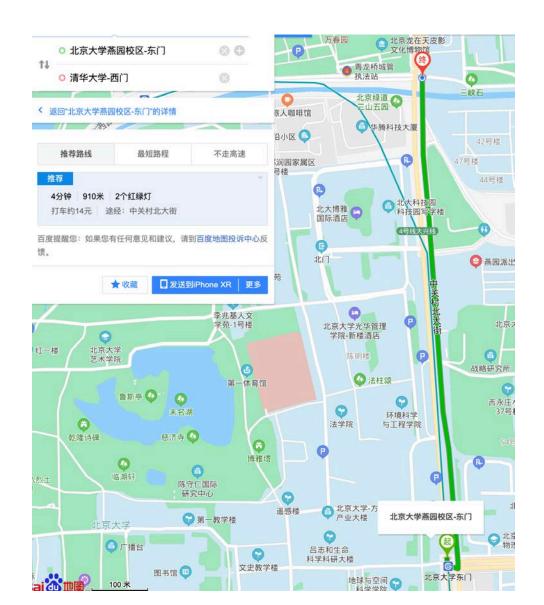


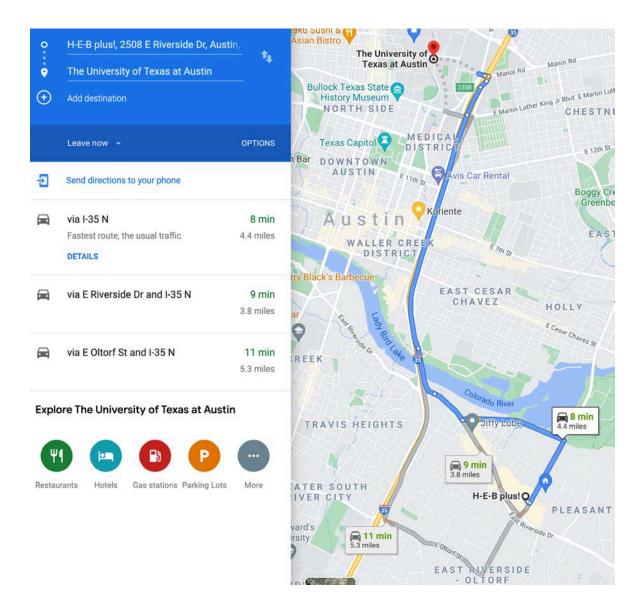
After Cut 2

Outline

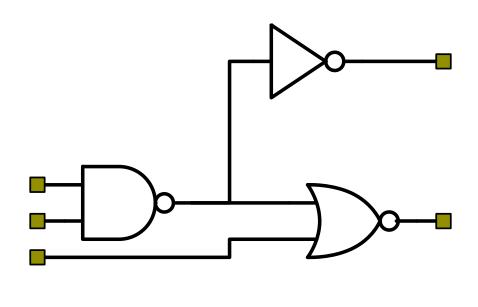
- Digital Design Flow from a IC design perspective
- Simulation
- Synthesis
- Placement
- Routing

What is Routing

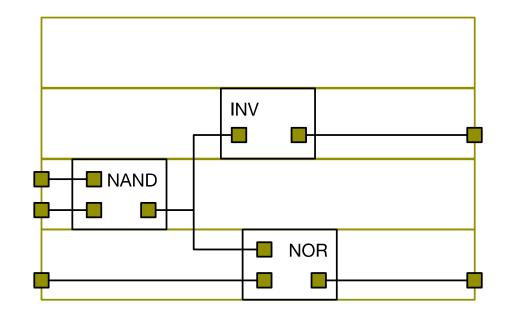




What is Routing

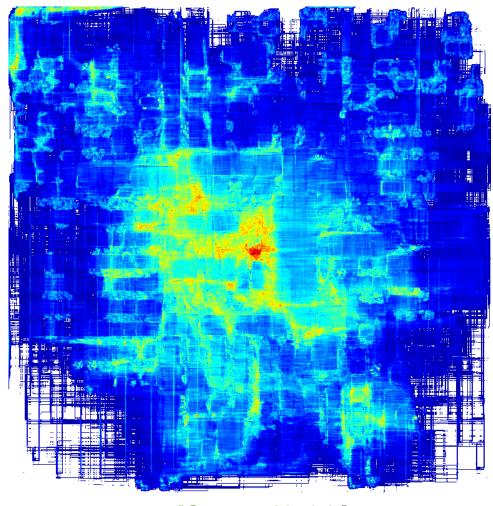




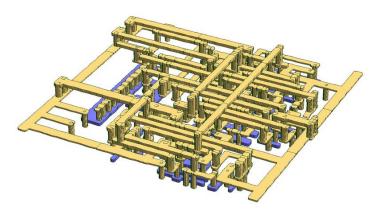


Placement and Routing

What is Routing



[Curtesy Umich]



A zoom-in 3D view [curtesy samyzaf]

Challenging problem

- 10+ metal layers
- Millions of nets
- May be highly congested
- Minimize wirelength

Routing Problem Formulation

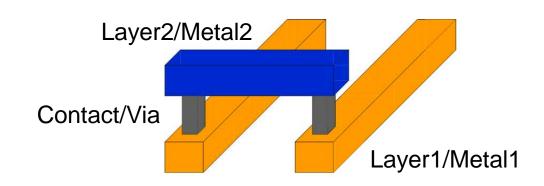
- Apply it after floorplanning/placement
- Input
 - Netlist
 - Timing budget for, typically, critical nets
 - Locations of blocks and locations of pins

Output

Geometric layouts of all nets

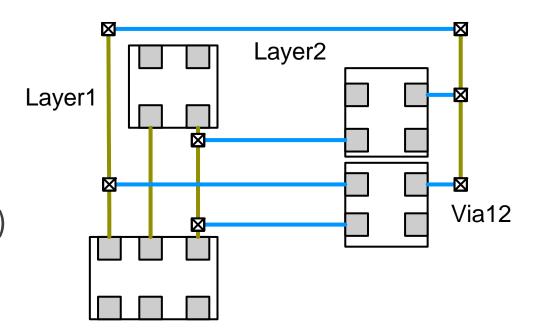
Objective

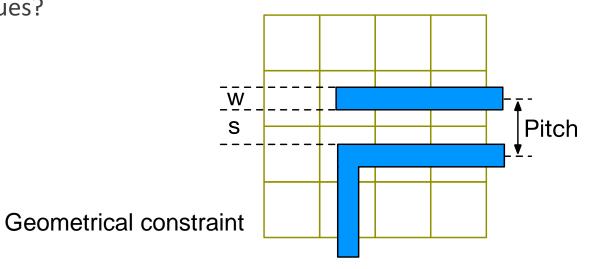
- Minimize the total wire length, the number of vias, or just completing all connections without increasing the chip area.
- Each net meets its timing budget



The Routing Constraints

- Placement constraint
- Number of routing layers
- Delay constraint
- Meet all geometrical constraints (design rules)
- Physical/Electrical/Manufacturing constraints:
 - Crosstalk
 - Process variations, yield, or lithography issues?





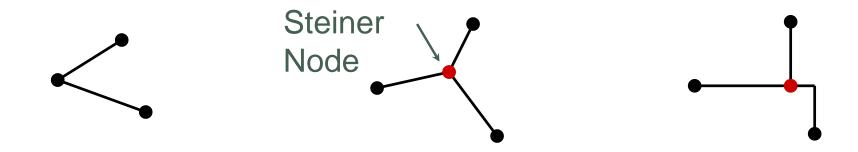
Steiner Tree

- For a multi-pin net, we can construct a spanning tree to connect all the pins together.
- But the wire length will be large.
- Better use Steiner Tree:

A tree connecting all pins and some additional nodes (Steiner nodes).

Rectilinear Steiner Tree:

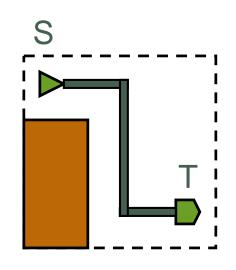
Steiner tree in which all the edges run horizontally and vertically.



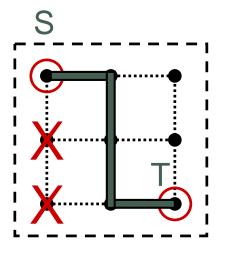
Maze Routing Problem

- Input
 - A planar rectangular grid graph.
 - ─ Two points S and T on the graph.
 - Obstacles modeled as blocked vertices.
- Objective
 - Find the shortest path connecting S and T.
- This technique can be used in global or detailed routing problems.

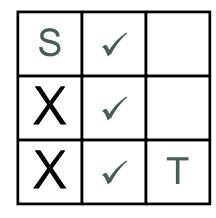
Grid Graph



Area Routing

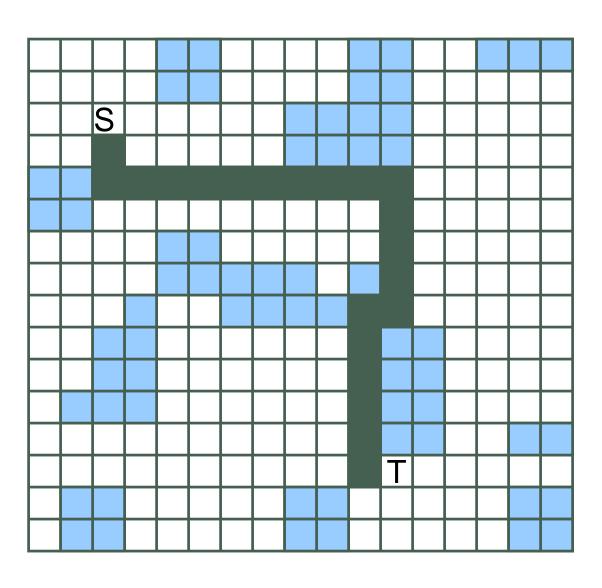


Grid Graph (Maze)



Simplified Representation

Maze Routing



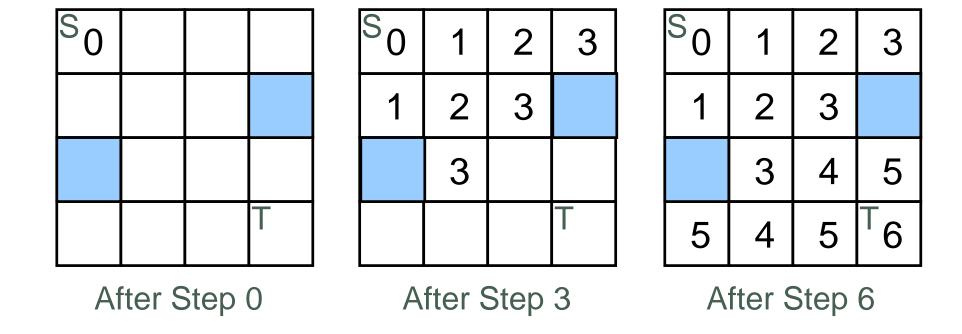
Lee's Algorithm

- Basic idea
- A Breadth-First Search (BFS) of the grid graph.
- Always find the shortest path possible.
- Consists of two phases:
 - Wave Propagation
 - Retrace

S ₀	1	2	3
1	2	3	
	3	4	5
5	4	5	^T 6

Wave Propagation

- At step k, all vertices at Manhattan-distance k from S are labeled with k.
- A Propagation List (FIFO) is used to keep track of the vertices to be considered next.



Retrace

- Trace back the actual route.
- Starting from *T*.
- At vertex with k, go to any vertex with label k-1.

So	1	2	3
- 🕇	-2←	3	
	3	4	5
5	4	- 5	<u>⊤</u> 6

Final labeling

Concurrent Approach

- Consider all the nets simultaneously.
- Formulate as an integer program.
- Given

Nets	Set of possible routing trees	
net 1	$T_{11}, T_{12}, \dots, T_{1k_1}$	
:	•	
net n	$T_{n1}, T_{n2}, \dots, T_{nk_n}$	

 L_{ij} = Total wire length of T_{ij} C_e = Capacity of edge e

Determine variable x_{ij} s.t. $x_{ij} = 1$ if T_{ij} is used $x_{ij} = 0$ otherwise.

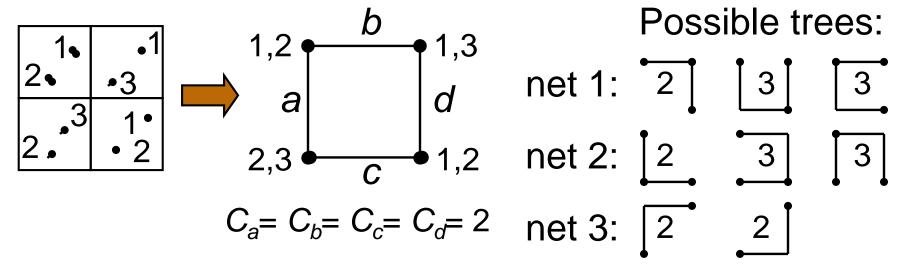
Integer Programming

Min.
$$\sum_{i=1}^{n} \sum_{j=1}^{k_i} L_{ij} \times x_{ij}$$
s.t.
$$\sum_{j=1}^{k_i} x_{ij} = 1 \quad \text{for all } i = 1, ..., n$$

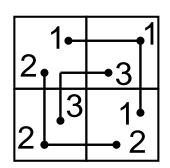
$$\sum_{i,j \text{ s.t. } e \in T_{ij}} x_{ij} \leq C_e \quad \text{for all edge } e$$

$$x_{ij} = 0 \text{ or } 1 \quad \forall i, j$$

Example



Solution



Min.
$$2x_{11} + 3x_{12} + 3x_{13} + 2x_{21} + 3x_{22} + 3x_{23} + 2x_{31} + 2x_{32}$$

 $\begin{cases} x_{11} + x_{12} + x_{13} = 1; \end{cases}$

s.t.
$$\begin{cases} x_{21} + x_{22} + x_{23} = 1; & \text{What are the constraints} \\ x_{31} + x_{32} = 1; & \text{for edge capacity?} \\ x_{ij} = 0 \text{ or } 1 \quad \forall i, j; \quad \boxed{x_{12} + x_{13} + x_{21} + x_{23} + x_{31} < C_a} \end{cases}$$

$$x_{12} + x_{13} + x_{21} + x_{23} + x_{31} < C_a$$

Integer Programming Approach

- Standard techniques to solve IP.
- No net ordering. Give global optimum.
- Can be extremely slow, especially for large problems.
- To make it faster, a fewer choices of routing trees for each net can be used. May make the problem infeasible or give a bad solution.
- Determining a good set of choices of routing trees is a hard problem by itself.

Hierarchical Approach to Speed Up IP

- Large Integer Programs are difficult to solve.
- ➡ Hierarchical Approach reduces global routing to routing problems on a 2x2 grid.
- Decompose recursively in a top-down fashion.
- Those 2x2 routing problems can be solved optimally by integer programming formulation.